

**REMARKS**

Claims 1-20 are pending.

**I. REPLY TO REJECTIONS**

**A. 35 U.S.C. § 112, First Paragraph**

On page 3, item 3 of the Office Action, claims 6, 8, 10, 11, 15 and 20 are rejected under 35 U.S.C. § 112, first paragraph, for allegedly failing to comply with the written description requirement. The rejection is respectfully traversed.

It is respectfully submitted that claims 6, 8, 10, 11, 15, and 20 are sufficiently supported by the written description in the disclosure, as to reasonably convey to one of ordinary skill in the art that the inventors, at the time the application was filed, had possession of the claimed invention. According to MPEP § 2163.02 (pg. 2100-177), the Applicants show possession of the claimed invention by describing the claimed invention with all its limitations using such descriptive means as words, structures, figures, diagrams, and formulas that fully set forth the claimed invention. It is noted that the permissible disclosure includes the written description and the drawings.

As to claim 6, the feature “a carrier module body having a latch and a through hole, wherein one end of the through hole seats a semiconductor device and is configured to hold the semiconductor device with a vacuum, and the other end of the through hole is aligned and

communicates with the vacuum tube,” is supported in paragraphs [0038] and [0045] of the specification, in view of Figs. 3 and 4A and 4B.

As to claim 8, the feature “wherein the supplementary housing includes an annular pusher formed around the supplementary housing for receiving support from the first elastic member,” is supported in paragraphs [0026] and [0027] of the specification, in view of Fig. 4A.

As to claim 10, the feature “wherein the vacuum tube and the through hole are configured to keep a vacuum when mated,” is supported in paragraphs [0028] and [0029] of the specification in view of Fig. 4A. As to claim 11, the feature “wherein an O-ring is fitted to one of an end of the vacuum tube and an end of the through hole, to thereby keep the vacuum,” is supported in paragraphs [0015] and [0029] of the specification in view of Fig. 4A.

As to claim 15, the feature “a telescoping housing having a first internal vacuum conduit, and a carrier module having a latch and a second internal vacuum conduit having a first and second end,” and “wherein both the latch and the second end of the second internal conduit are configured to hold a semiconductor device” are supported in paragraph [0013] at lines 5-6 and paragraph [0038] of the specification, in view of Figs. 4A.

As to claim 20, the feature “wherein the presence of the semiconductor device on the second end of the second internal conduit is determined by the presence of a vacuum formed in the first and second internal conduits,” is supported in paragraphs [0045] and [0046] of the specification.

In view of such sufficient descriptions and support, one of ordinary skill in the art is apprised that the inventors had possession of the invention as claimed at the time of the application. Withdrawal of the rejection is respectfully requested.

**B. 35 U.S.C. § 102**

On page 3, item 5 of the Office Action, claims 1-5 are rejected under 35 U.S.C. § 102(e) over U.S. Publication No. 2004/0251460 to Lee et al. (hereinafter “Lee”). The rejection is respectfully traversed.

The Examiner asserts that Lee discloses a carrier module body (an alignment shuttle 500) having a pass through hole (a through hole 512), a housing (a plate 501) over the carrier module body (the alignment shuttle 500), a supplementary housing (a seating block 510) fitted in lower part of the housing (plate 501) to be movable in up/down directions. If so, Lee fails to disclose a housing located over the carrier module body because Lee discloses that the plate 501 (alleged to be the housing) is included in the alignment shuttle 500 (alleged to be the carrier module body) (see paragraph [0028] of Lee).

Furthermore, the device disclosed in Lee is not configured such that when the semiconductor device is brought into contact with a test socket, and tested, the semiconductor device is held with a vacuum formed through the pass through hole in the carrier module body and the vacuum tube while the at least one pair of latches releases the semiconductor device. As shown in Figs. 8 and 9 of Lee, the electrical output leads B of the semiconductor device S are

located on the underside of the semiconductor device when the semiconductor device is held by a vacuum of the vacuum tube 512. Thus, the semiconductor device cannot be brought into contact with a test socket for testing while it is held by a vacuum in the Lee device. Because Lee fails to disclose the above-discussed relationships between the housing and the carrier module body, claim 1 is patentable over the applied reference. Claims 2-5, which depend from claim 1, are likewise patentable over the applied reference for at least the reasons discussed above and for the additional features they recite. Withdrawal of the rejection is respectfully requested.

On page 5, item 6 of the Office Action, claims 6-14 are rejected under 35 U.S.C. § 102(e) over Lee. The rejection is respectfully traversed.

The Examiner asserts that Lee discloses a housing (a plate 501) having an internal accommodating space, a supplemental housing (a seating block 510) that is partially accommodated in the internal accommodating space of the housing and having a vacuum tube (presumably a through hole 512 as the through hole 512 is in the seating block 510), and a carrier module body (presumably plate 501 as the latch 521 is on the plate 501), having a latch (presumably latch 521) having a through hole (through hole 512). If so, Lee fails to disclose a through hole that seats a semiconductor device in one end and the other end of the through hole being aligned and communicating with a vacuum tube, as recited in claim 6. In the Lee device, the vacuum tube of the supplemental housing (alleged to be the through hole 512) and the through hole carrier module body (alleged to also be the through hole 512) cannot be aligned as recited in claim 6.

Because the relationships recited in claim 6 cannot be satisfied by the Lee device, claim 6 is patentable over the applied reference. Claims 7-14 which depend from claim 6 are likewise patentable over the applied reference for at least the reasons discussed above and for the additional features they recite. Withdrawal of the rejection is respectfully requested.

On page 6, item 7 of the Office Action, claims 15-20 are rejected under 35 U.S.C. § 103(e) over Lee. The rejection is respectfully traversed.

The Examiner asserts that Lee discloses a telescope housing (presumably the seating block 510 as it is able to move up/down within the plate 501), having a first internal vacuum conduit (noted as being a lower portion of through hole 512), and a carrier module (presumably plate 501), having a latch (latch 521), and a second internal vacuum conduit (presumably also the through hole 512) having a first and second end. Applicant disagrees with this reading because the Examiner has apparently used a single vacuum conduit (passage 512) to satisfy two distinctly different claim features of claim 15, which recites both a “first internal vacuum conduit” and a “second internal vacuum conduit.” Furthermore, claim 15 requires a second internal vacuum conduit in the carrier module. The Examiner asserts that the plate 501 is the carrier module. If so, then the passage 512 is not an internal vacuum conduit within the carrier module (the plate 501). Instead, the passage 512 is in the seating block 510, which corresponds to the claimed telescoping housing.

Because the Lee device also cannot satisfy the relationships recited in claim 15, claim 15 is allowable. Claims 16-20, which depend from claim 15, are likewise patentable over the applied

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reference and for the additional features they recite. Withdrawal of the rejection is respectfully requested.

II. **CONCLUSION**

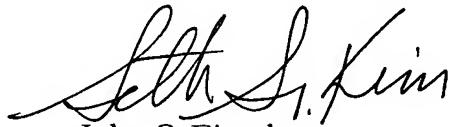
In view of the foregoing amendments and remarks, it is respectfully submitted that the application is in condition for allowance. Favorable consideration and prompt allowance are earnestly solicited. If the Examiner believes that any additional changes would place the application in better condition for allowance, the Examiner is invited to contact the undersigned attorney, **Seth S. Kim**, at the telephone number listed below.

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To the extent necessary, a petition for an extension of time under 37 C.F.R. 1.136 is hereby made. Please charge any shortage in fees due in connection with the filing of this, concurrent and future replies, including extension of time fees, to Deposit Account 16-0607 and please credit any excess fees to such deposit account.

Respectfully submitted,  
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